

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}		K/W
BCR158		≤ 240	
BCR158W		≤ 105	

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Collector-emitter breakdown voltage $I_C = 100\ \mu\text{A}$, $I_B = 0$	$V_{(BR)CEO}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10\ \mu\text{A}$, $I_E = 0$	$V_{(BR)CBO}$	50	-	-	
Collector-base cutoff current $V_{CB} = 40\ \text{V}$, $I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 5\ \text{V}$, $I_C = 0$	I_{EBO}	-	-	164	μA
DC current gain ²⁾ $I_C = 5\ \text{mA}$, $V_{CE} = 5\ \text{V}$	h_{FE}	70	-	-	-
Collector-emitter saturation voltage ²⁾ $I_C = 10\ \text{mA}$, $I_B = 0.5\ \text{mA}$	V_{CEsat}	-	-	0.3	V
Input off voltage $I_C = 100\ \mu\text{A}$, $V_{CE} = 5\ \text{V}$	$V_{i(off)}$	0.4	-	0.8	
Input on voltage $I_C = 2\ \text{mA}$, $V_{CE} = 0.3\ \text{V}$	$V_{i(on)}$	0.5	-	1.1	
Input resistor	R_1	1.5	2.2	2.9	k Ω
Resistor ratio	R_1/R_2	0.042	0.047	0.052	-

AC Characteristics

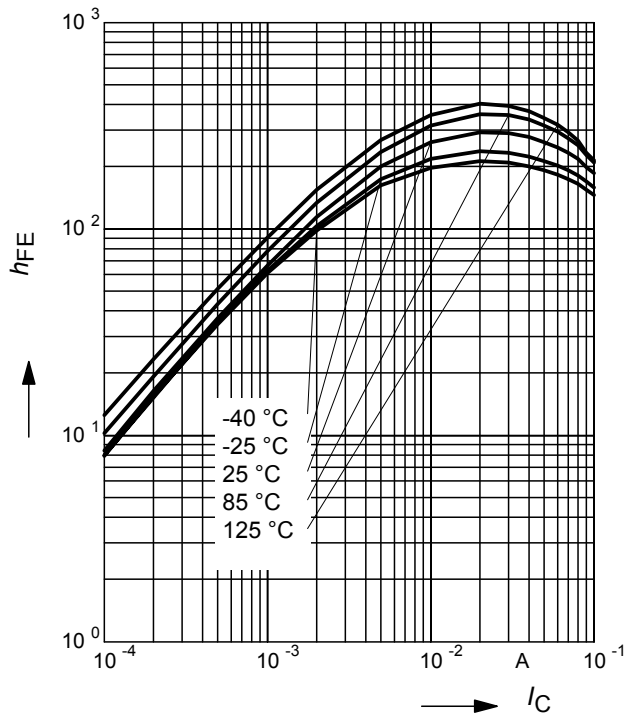
Transition frequency $I_C = 10\ \text{mA}$, $V_{CE} = 5\ \text{V}$, $f = 100\ \text{MHz}$	f_T	-	200	-	MHz
Collector-base capacitance $V_{CB} = 10\ \text{V}$, $f = 1\ \text{MHz}$	C_{cb}	-	3	-	pF

¹⁾For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

²⁾Pulse test: $t < 300\ \mu\text{s}$; $D < 2\%$

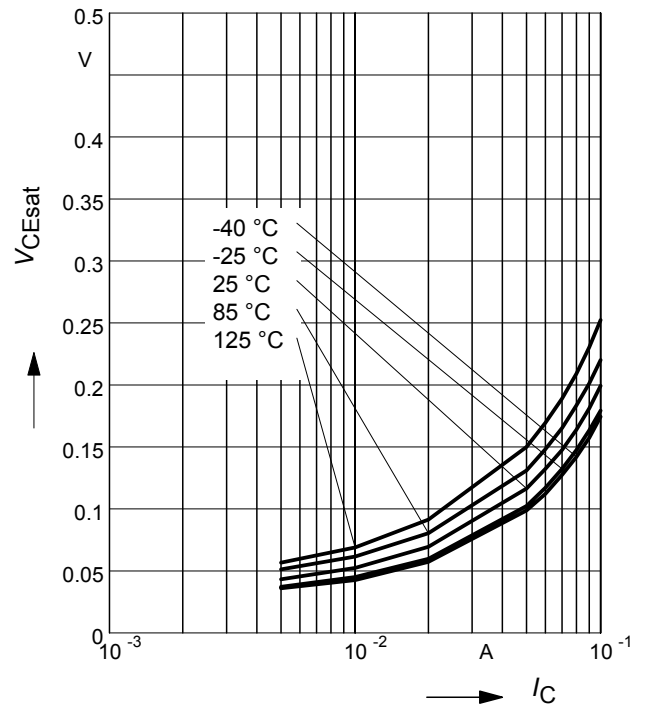
DC current gain $h_{FE} = f(I_C)$

$V_{CE} = 5V$ (common emitter configuration)



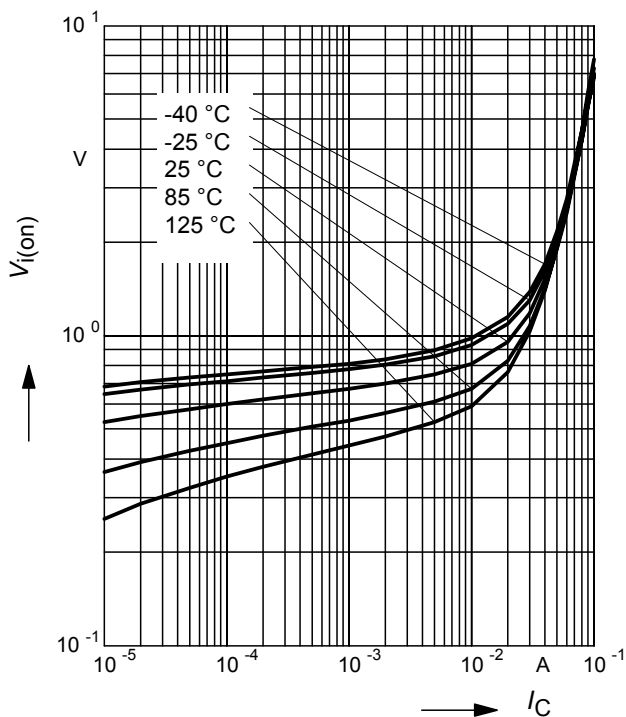
Collector-emitter saturation voltage

$V_{CEsat} = f(I_C)$, $I_C/I_B = 20$



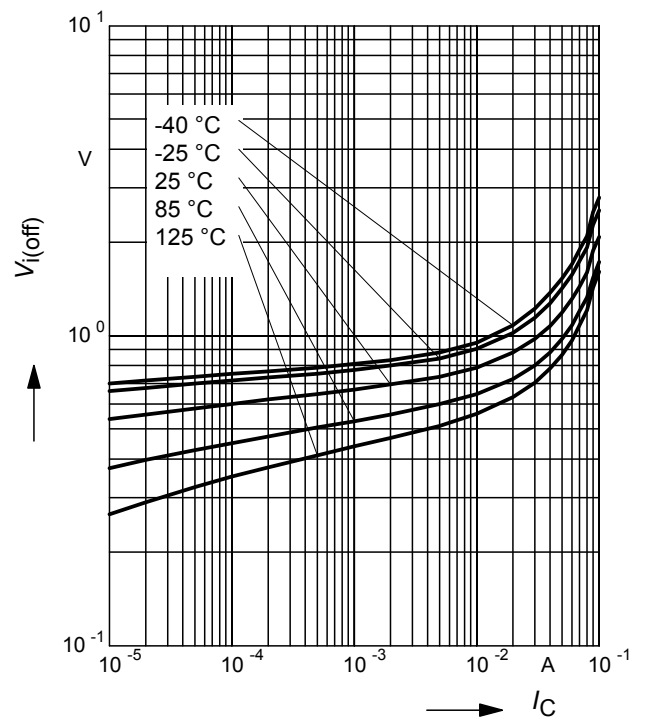
Input on Voltage $V_{i(on)} = f(I_C)$

$V_{CE} = 0.3V$ (common emitter configuration)



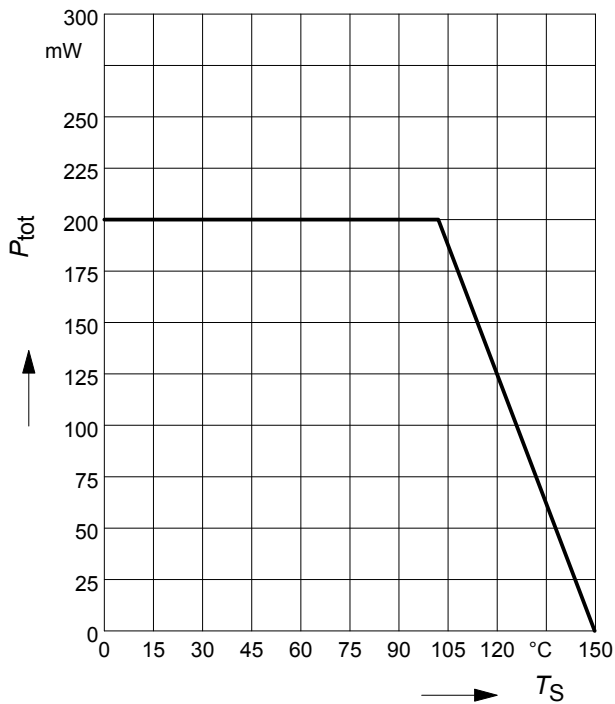
Input off voltage $V_{i(off)} = f(I_C)$

$V_{CE} = 5V$ (common emitter configuration)



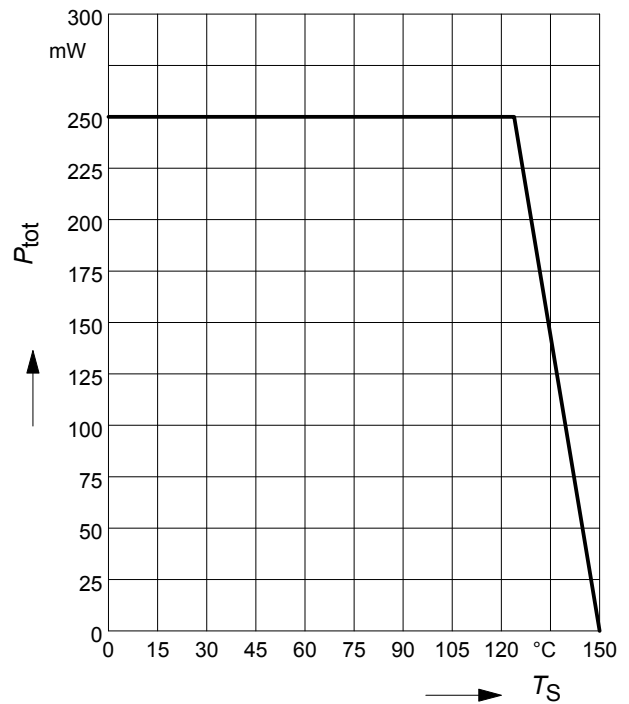
Total power dissipation $P_{\text{tot}} = f(T_S)$

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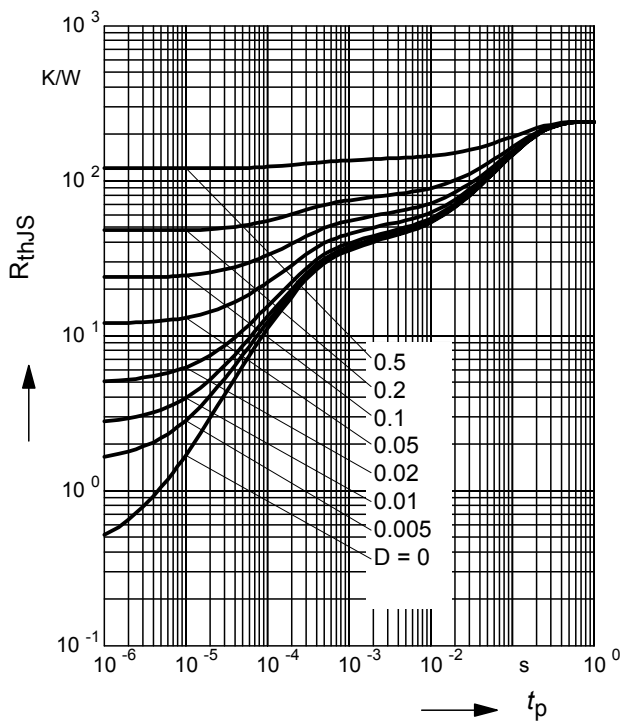
Total power dissipation $P_{\text{tot}} = f(T_S)$

BCR158W



Permissible Pulse Load $R_{\text{thJS}} = f(t_p)$

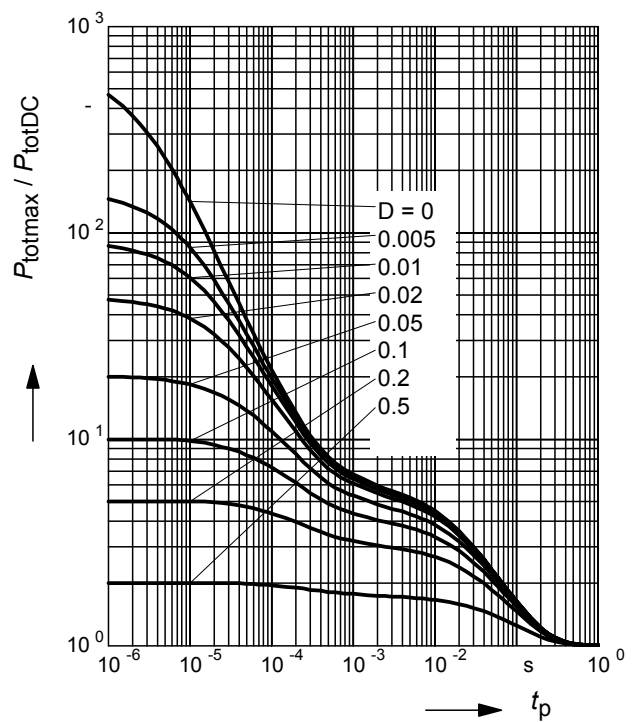
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Permissible Pulse Load

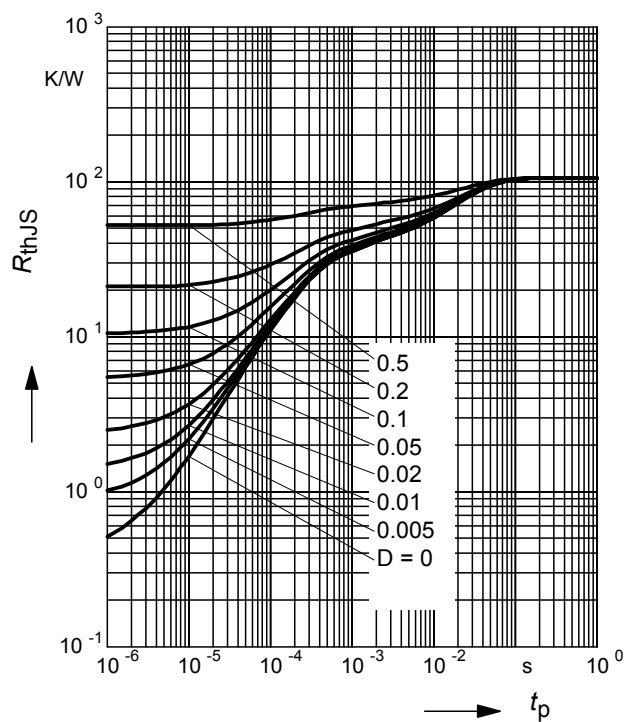
$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$

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Permissible Puls Load $R_{thJS} = f(t_p)$

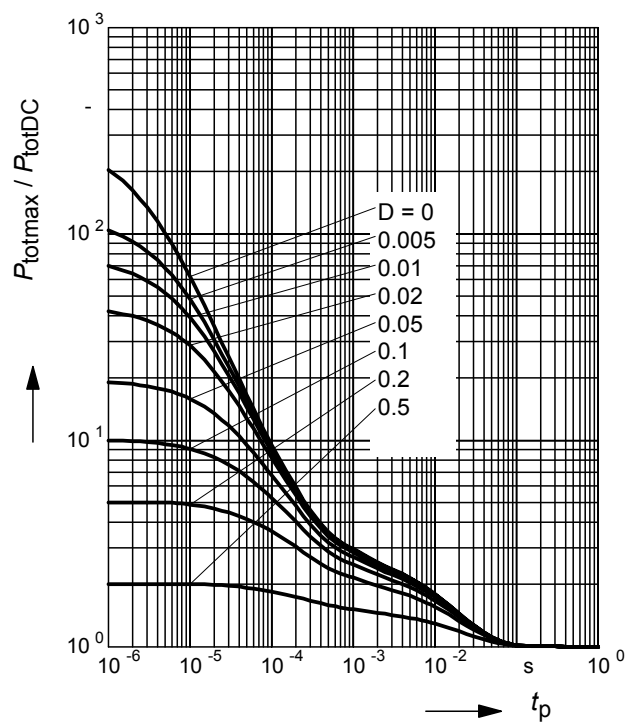
BCR158W



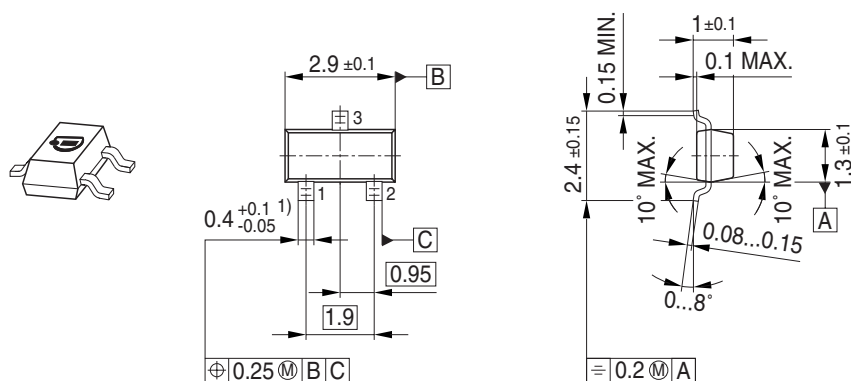
Permissible Pulse Load

$$P_{totmax}/P_{totDC} = f(t_p)$$

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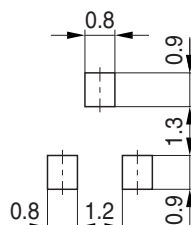


Package Outline

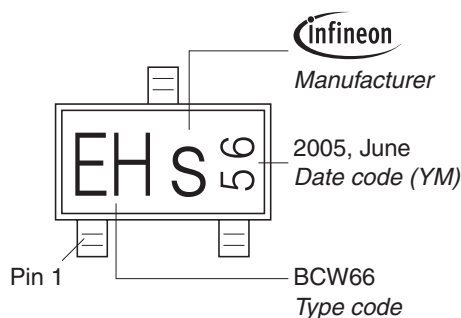


1) Lead width can be 0.6 max. in dambar area

Foot Print

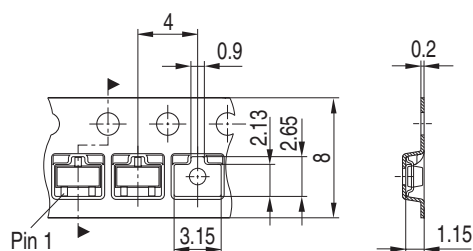


Marking Layout (Example)

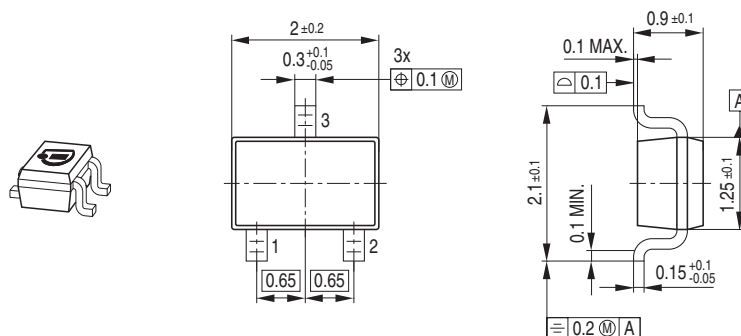


Standard Packing

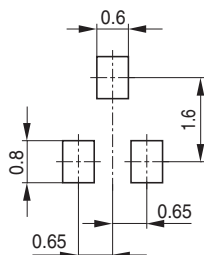
Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



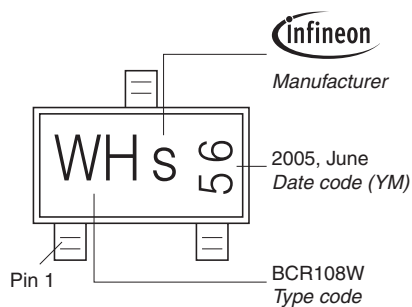
Package Outline



Foot Print

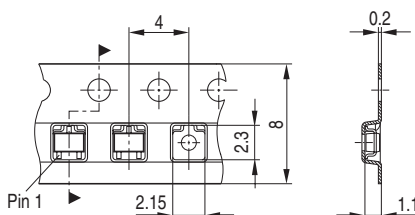


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel



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